

**SN5432, SN54LS32, SN54S32,
SN7432, SN74LS32, SN74S32**
QUADRUPLE 2-INPUT POSITIVE-OR GATES
DECEMBER 1983 - REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

SN5432, SN54LS32, SN54S32 . . . J OR W PACKAGE
SN7432 . . . N PACKAGE
SN74LS32, SN74S32 . . . D OR N PACKAGE

description

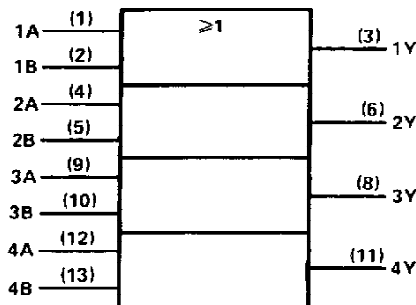
These devices contain four independent 2-input OR gates.

The SN5432, SN54LS32 and SN54S32 are characterized for operation over the full military range of -55°C to 125°C. The SN7432, SN74LS32 and SN74S32 are characterized for operation from 0°C to 70°C.

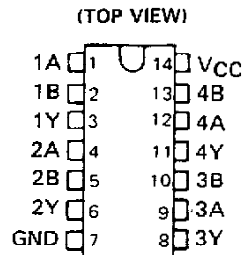
FUNCTION TABLE (each gate)

| INPUTS | | OUTPUT |
|--------|---|--------|
| A | B | Y |
| H | X | H |
| X | H | H |
| L | L | L |

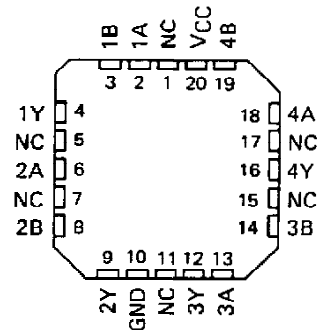
logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, or W packages.

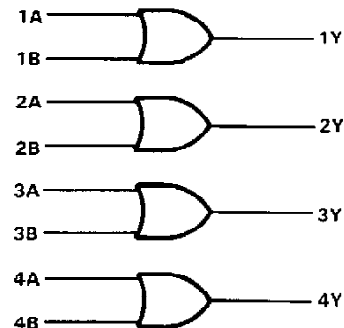


SN54LS32, SN54S32 . . . FK PACKAGE
(TOP VIEW)



NC - No internal connection

logic diagram



positive logic

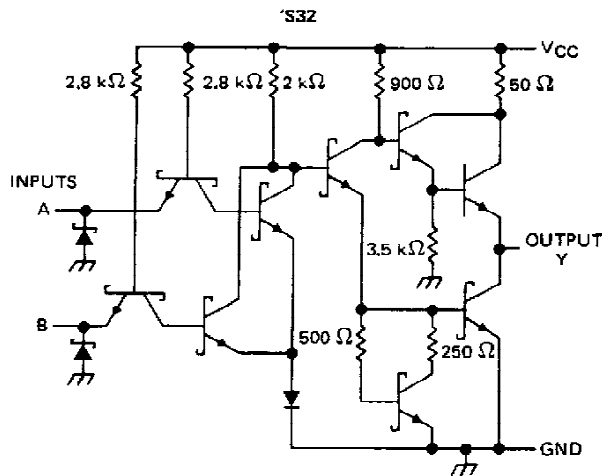
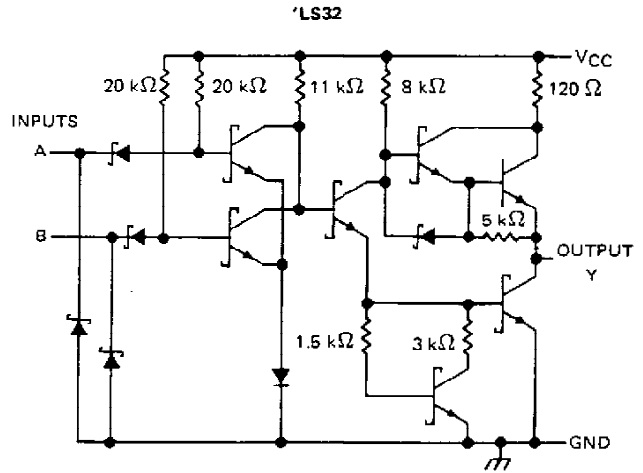
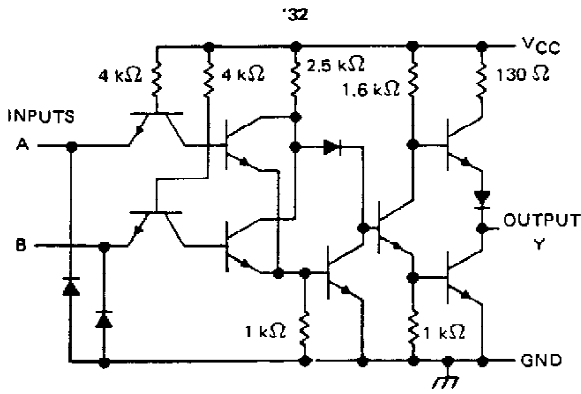
$$Y = A + B \text{ or } Y = \overline{\overline{A} \cdot \overline{B}}$$

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



**SN5432, SN54LS32, SN54S32,
SN7432, SN74LS32, SN74S32
QUADRUPLE 2-INPUT POSITIVE-OR GATES**

schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| | |
|--|----------------|
| Supply voltage, V _{CC} (see Note 1) | 7 V |
| Input voltage: '32, 'S32 | 5.5 V |
| 'LS32 | 7 V |
| Operating free-air temperature: SN54' | -55°C to 125°C |
| SN74' | 0°C to 70°C |
| Storage temperature range | -65°C to 150°C |

NOTE 1: Voltage values are with respect to network ground terminal.



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SN5432, SN7432

QUADRUPLE 2-INPUT POSITIVE-OR GATES

recommended operating conditions

| | SN5432 | | | SN7432 | | | UNIT |
|---|--------|-----|------|--------|-----|------|------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| V _{CC} Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| V _{IH} High-level input voltage | 2 | | | 2 | | | V |
| V _{IL} Low-level input voltage | | | 0.8 | | | 0.8 | V |
| I _{OH} High-level output current | | | -0.8 | | | -0.8 | mA |
| I _{OL} Low-level output current | | | 16 | | | 16 | mA |
| T _A Operating free-air temperature | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS † | SN5432 | | | SN7432 | | | UNIT |
|-------------------|---|--------|-------|------|--------|-------|------|------|
| | | MIN | TYP ‡ | MAX | MIN | TYP ‡ | MAX | |
| V _{IK} | V _{CC} = MIN, I _I = -12 mA | | | -1.5 | | | -1.5 | V |
| V _{OH} | V _{CC} = MIN, V _{IH} = 2 V, I _{OH} = -0.8 mA | 2.4 | 3.4 | | 2.4 | 3.4 | | V |
| V _{OL} | V _{CC} = MIN, V _{IL} = 0.8 V, I _{OL} = 16 mA | | 0.2 | 0.4 | | 0.2 | 0.4 | V |
| I _I | V _{CC} = MAX, V _I = 5.5 V | | | 1 | | | 1 | mA |
| I _{IH} | V _{CC} = MAX, V _I = 2.4 V | | | 40 | | | 40 | μA |
| I _{IL} | V _{CC} = MAX, V _I = 0.4 V | | | 1.6 | | | -1.6 | mA |
| I _{OS} § | V _{CC} = MAX | -20 | | -55 | -18 | | -55 | mA |
| I _{CCH} | V _{CC} = MAX, See Note 2 | | 15 | 22 | | 15 | 22 | mA |
| I _{CCL} | V _{CC} = MAX, V _I = 0 V | | 23 | 38 | | 23 | 38 | mA |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|--------------|-------------|--|-----|-----|-----|------|
| t _{PLH} | A or B | Y | R _L = 400 Ω, C _L = 15 pF | | 10 | 15 | ns |
| t _{PHL} | | | | | 14 | 22 | ns |

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

SN54LS32, SN74LS32

QUADRUPLE 2-INPUT POSITIVE-OR GATES

recommended operating conditions

| | SN54LS32 | | | SN74LS32 | | | UNIT |
|---|----------|-----|------|----------|-----|------|------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| V _{CC} Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| V _{IH} High-level input voltage | 2 | | | 2 | | | V |
| V _{IL} Low-level input voltage | | | 0.7 | | | 0.8 | V |
| I _{OH} High-level output current | | | -0.4 | | | -0.4 | mA |
| I _{OL} Low-level output current | | | 4 | | | 8 | mA |
| T _A Operating free-air temperature | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS † | SN54LS32 | | | SN74LS32 | | | UNIT |
|-------------------|---|----------|-------|------|----------|-------|------|------|
| | | MIN | TYP ‡ | MAX | MIN | TYP ‡ | MAX | |
| V _{IK} | V _{CC} = MIN, I _I = -18 mA | | | -1.5 | | | -1.5 | V |
| V _{OH} | V _{CC} = MIN, V _{IH} = 2 V, I _{OH} = -0.4 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | V |
| V _{OL} | V _{CC} = MIN, V _{IL} = MAX, I _{OL} = 4 mA | | 0.25 | 0.4 | | 0.25 | 0.4 | V |
| | V _{CC} = MIN, V _{IL} = MAX, I _{OL} = 8 mA | | | | | 0.35 | 0.5 | |
| I _I | V _{CC} = MAX, V _I = 7 V | | | 0.1 | | | 0.1 | mA |
| I _{IH} | V _{CC} = MAX, V _I = 2.7 V | | | 20 | | | 20 | µA |
| I _{IL} | V _{CC} = MAX, V _I = 0.4 V | | | -0.4 | | | -0.4 | mA |
| I _{OS} § | V _{CC} = MAX | -20 | | -100 | -20 | | -100 | mA |
| I _{CCH} | V _{CC} = MAX, See Note 2 | | 3.1 | 6.2 | | 3.1 | 6.2 | mA |
| I _{CCL} | V _{CC} = MAX, V _I = 0 V | | 4.9 | 9.8 | | 4.9 | 9.8 | mA |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|--------------|-------------|---|-----|-----|-----|------|
| t _{PLH} | A or B | Y | R _L = 2 kΩ, C _L = 15 pF | | 14 | 22 | ns |
| t _{PHL} | | | | | 14 | 22 | ns |

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TEXAS
INSTRUMENTS

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SN54S32, SN74S32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

recommended operating conditions

| | SN54S32 | | | SN74S32 | | | UNIT |
|---|---------|-----|-----|---------|-----|------|------|
| | MIN | NOM | MAX | MIN | NOM | MAX | |
| V _{CC} Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| V _{IH} High-level input voltage | 2 | | | 2 | | | V |
| V _{IL} Low-level input voltage | | | 0.8 | | | 0.8 | V |
| I _{OH} High-level output current | | | -1 | | | -1 | mA |
| I _{OL} Low-level output current | | | 20 | | | 20 | mA |
| T _A Operating free-air temperature | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS † | SN54S32 | | | SN74S32 | | | UNIT |
|-------------------|---|---------|-------|------|---------|-------|------|------|
| | | MIN | TYP ‡ | MAX | MIN | TYP ‡ | MAX | |
| V _{IK} | V _{CC} = MIN, I _I = -18 mA | | | -1.2 | | | -1.2 | V |
| V _{OH} | V _{CC} = MIN, V _{IH} = 2 V, I _{OH} = -1 mA | 2.5 | 3.4 | | 2.7 | 3.4 | | V |
| V _{OL} | V _{CC} = MIN, V _{IL} = 0.8 V, I _{OL} = 20 mA | | | 0.5 | | | 0.5 | V |
| I _I | V _{CC} = MAX, V _I = 5.5 V | | | 1 | | | 1 | mA |
| I _{IH} | V _{CC} = MAX, V _I = 2.7 V | | | 50 | | | 50 | μA |
| I _{IL} | V _{CC} = MAX, V _I = 0.5 V | | | -2 | | | -2 | mA |
| I _{OS} § | V _{CC} = MAX | -40 | | -100 | -40 | | -100 | mA |
| I _{CCH} | V _{CC} = MAX, See Note 2 | | 18 | 32 | | 18 | 32 | mA |
| I _{CCL} | V _{CC} = MAX, V _I = 0 V | | 38 | 68 | | 38 | 68 | mA |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

NOTE 2: One input at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|--------------|-------------|--|-----|-----|-----|------|
| t _{PLH} | A or B | Y | R _L = 280 Ω, C _L = 15 pF | | 4 | 7 | ns |
| t _{PHL} | | | | | 4 | 7 | ns |
| t _{PLH} | A or B | Y | R _L = 280 Ω, C _L = 50 pF | | 5 | | ns |
| t _{PHL} | | | | | 5 | | ns |

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.


**TEXAS
INSTRUMENTS**

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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-9557401QCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| 5962-9557401QDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| 5962-9557401QDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501B2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| JM38510/30501B2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| JM38510/30501BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501SCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501SCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501SDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501SDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SN5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN7432N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN7432N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN7432N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN7432N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN7432NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN7432NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRE4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRE4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRG4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRG4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| | | | | | | no Sb/Br) | | |
| SN74LS32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN74LS32J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN74LS32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74LS32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74LS32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN74S32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74S32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74S32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SNJ5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ5432W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ5432W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54LS32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54LS32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54LS32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54LS32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54S32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54S32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SNJ54S32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54S32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



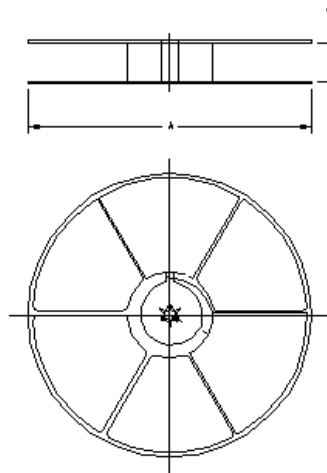
Carrier tape design is defined largely by the component length, width, and thickness.

| |
|--|
| A_o = Dimension designed to accommodate the component width. |
| B_o = Dimension designed to accommodate the component length. |
| K_o = Dimension designed to accommodate the component thickness. |
| W = Overall width of the carrier tape. |
| P = Pitch between successive cavity centers. |



TAPE AND REEL INFORMATION

| Device | Package | Pins | Site | Reel Diameter (mm) | Reel Width (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|---------|------|------|--------------------|-----------------|---------|---------|---------|---------|--------|---------------|
| SN74LS32DBR | DB | 14 | MLA | 330 | 16 | 8.2 | 6.6 | 2.5 | 12 | 16 | Q1 |
| SN74LS32DR | D | 14 | MLA | 330 | 16 | 6.5 | 9.0 | 2.1 | 8 | 16 | Q1 |
| SN74LS32NSR | NS | 14 | MLA | 330 | 16 | 8.2 | 10.5 | 2.5 | 12 | 16 | Q1 |
| SN74S32DR | D | 14 | MLA | 330 | 16 | 6.5 | 9.0 | 2.1 | 8 | 16 | Q1 |
| SN74S32NSR | NS | 14 | MLA | 330 | 16 | 8.2 | 10.5 | 2.5 | 12 | 16 | Q1 |



TAPE AND REEL BOX INFORMATION

| Device | Package | Pins | Site | Length (mm) | Width (mm) | Height (mm) |
|-------------|---------|------|------|-------------|------------|-------------|
| SN74LS32DBR | DB | 14 | MLA | 342.9 | 336.6 | 28.58 |
| SN74LS32DR | D | 14 | MLA | 342.9 | 336.6 | 28.58 |
| SN74LS32NSR | NS | 14 | MLA | 342.9 | 336.6 | 28.58 |
| SN74S32DR | D | 14 | MLA | 342.9 | 336.6 | 28.58 |
| SN74S32NSR | NS | 14 | MLA | 342.9 | 336.6 | 28.58 |



J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-9557401QCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| 5962-9557401QDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| 5962-9557401QDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501B2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| JM38510/30501B2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| JM38510/30501BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501BDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501SCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501SCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| JM38510/30501SDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| JM38510/30501SDA | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SN5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SN7432N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN7432N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN7432N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN7432N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN7432NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN7432NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRE4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRE4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRG4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DBRG4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| | | | | | | no Sb/Br) | | |
| SN74LS32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN74LS32J | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI |
| SN74LS32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74LS32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74LS32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74LS32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LS32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN74S32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74S32N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI |
| SN74S32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74S32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74S32NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SNJ5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ5432J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ5432W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ5432W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54LS32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54LS32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54LS32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54LS32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54LS32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54S32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54S32FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| SNJ54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| SNJ54S32J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 SNPB | N / A for Pkg Type |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SNJ54S32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |
| SNJ54S32W | ACTIVE | CFP | W | 14 | 1 | TBD | A42 | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

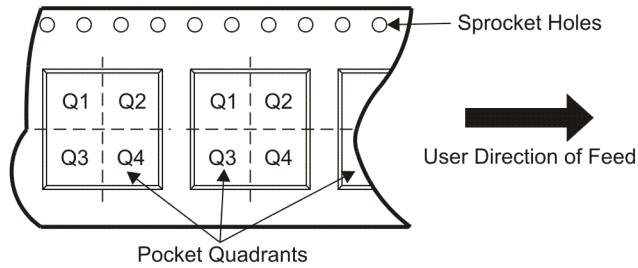
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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74LS32DBR | SSOP | DB | 14 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LS32DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74LS32NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74S32DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74S32NSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74LS32DBR | SSOP | DB | 14 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74LS32DR | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |
| SN74LS32NSR | SO | NS | 14 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74S32DR | SOIC | D | 14 | 2500 | 346.0 | 346.0 | 33.0 |
| SN74S32NSR | SO | NS | 14 | 2000 | 346.0 | 346.0 | 33.0 |

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

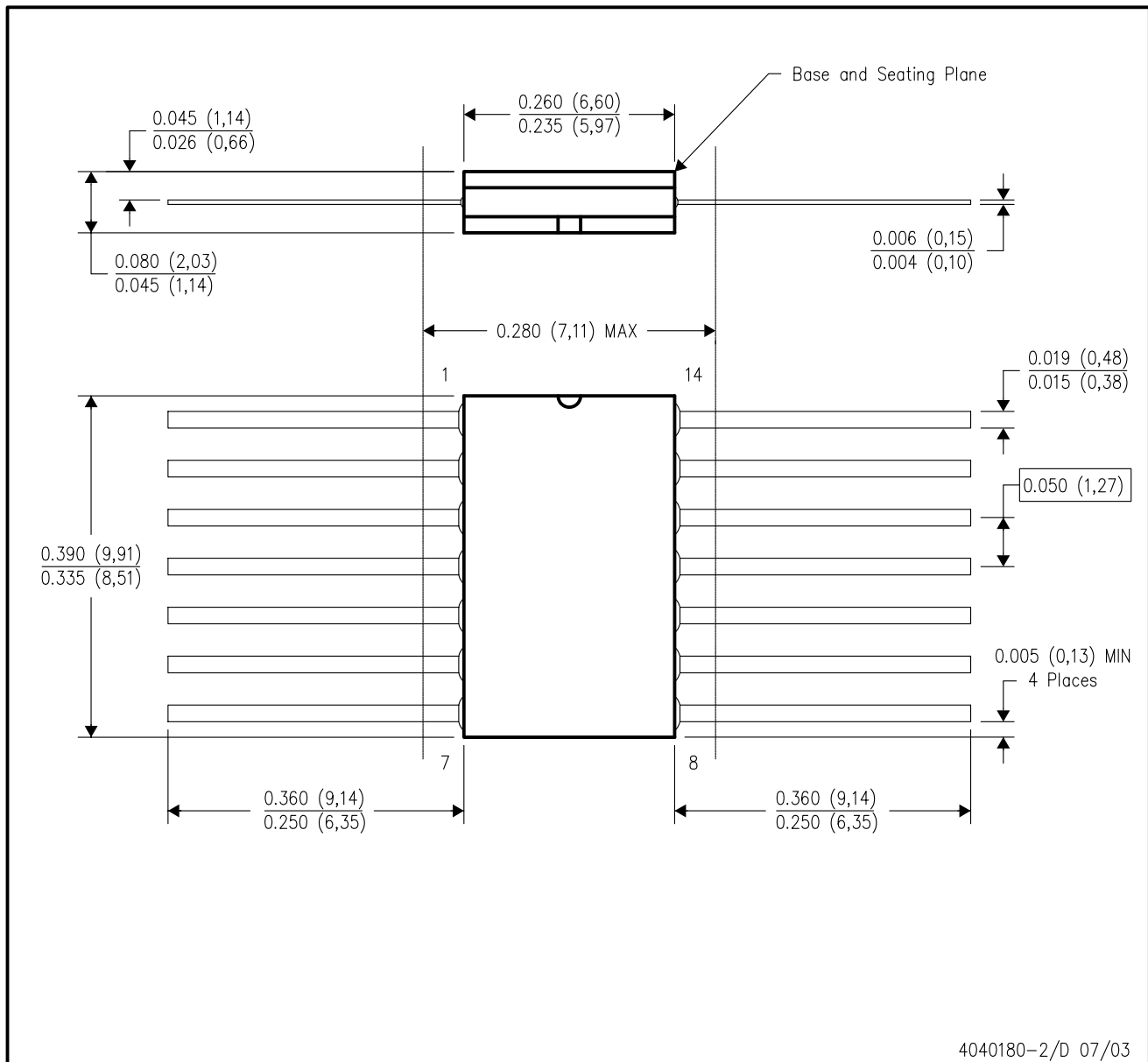
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

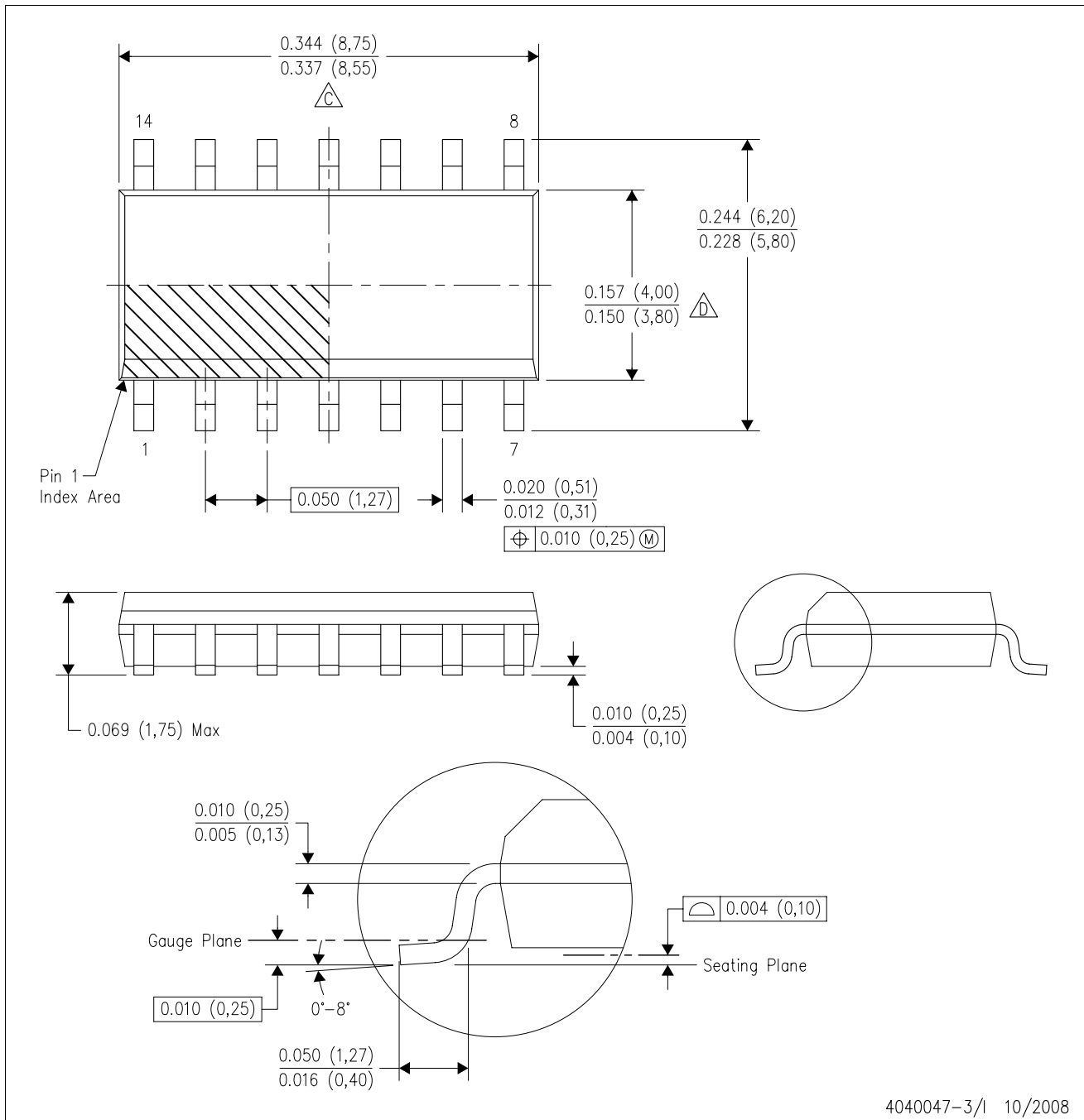
CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

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